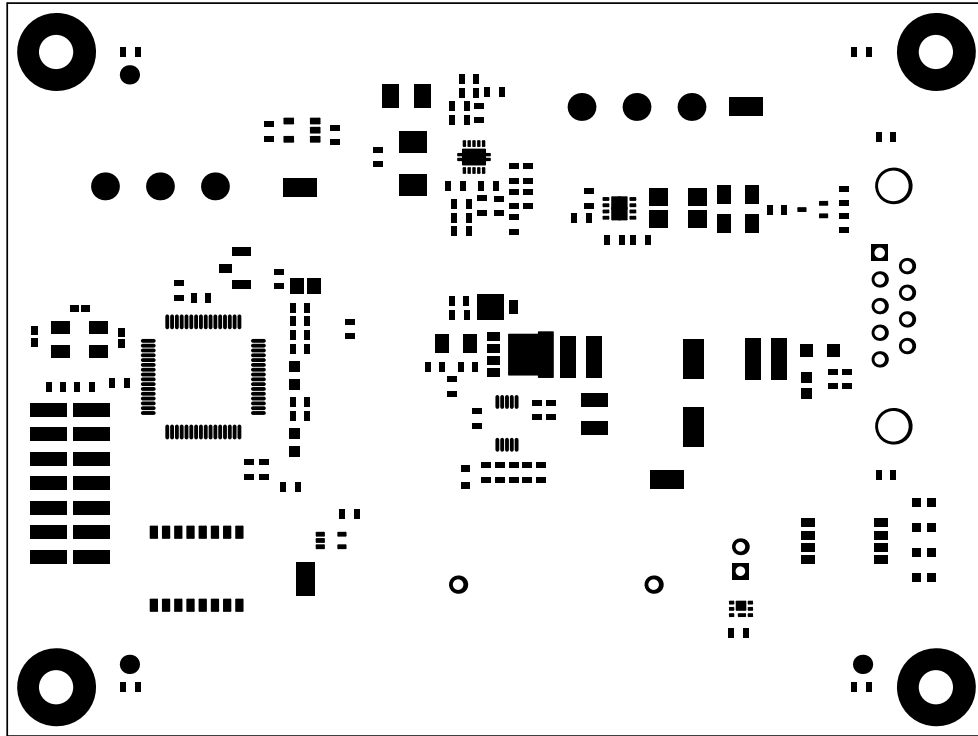
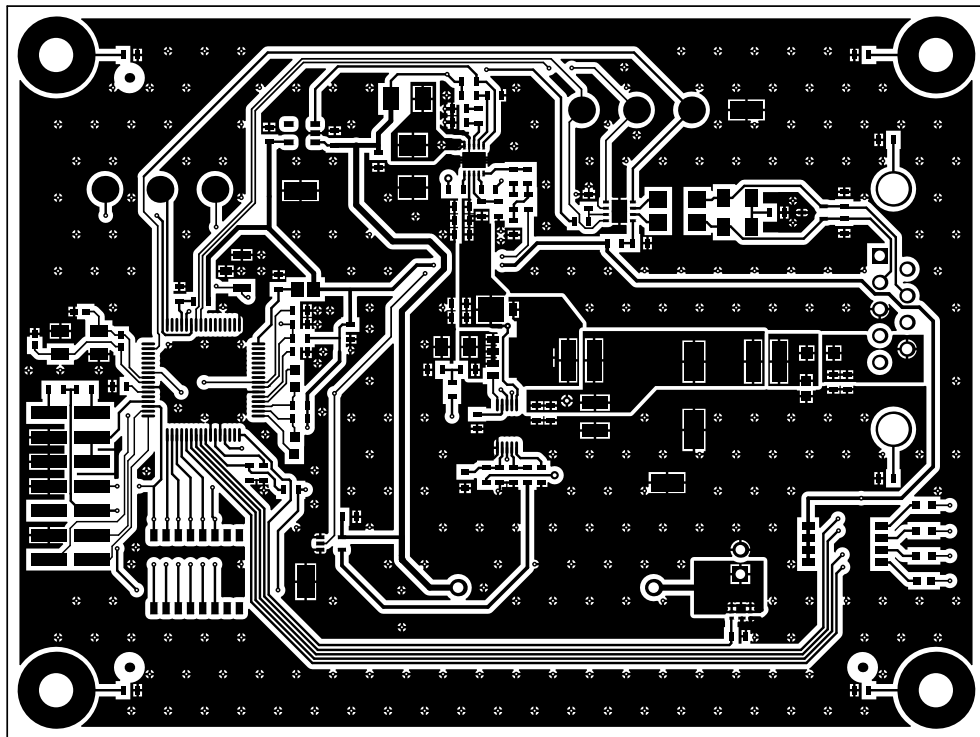


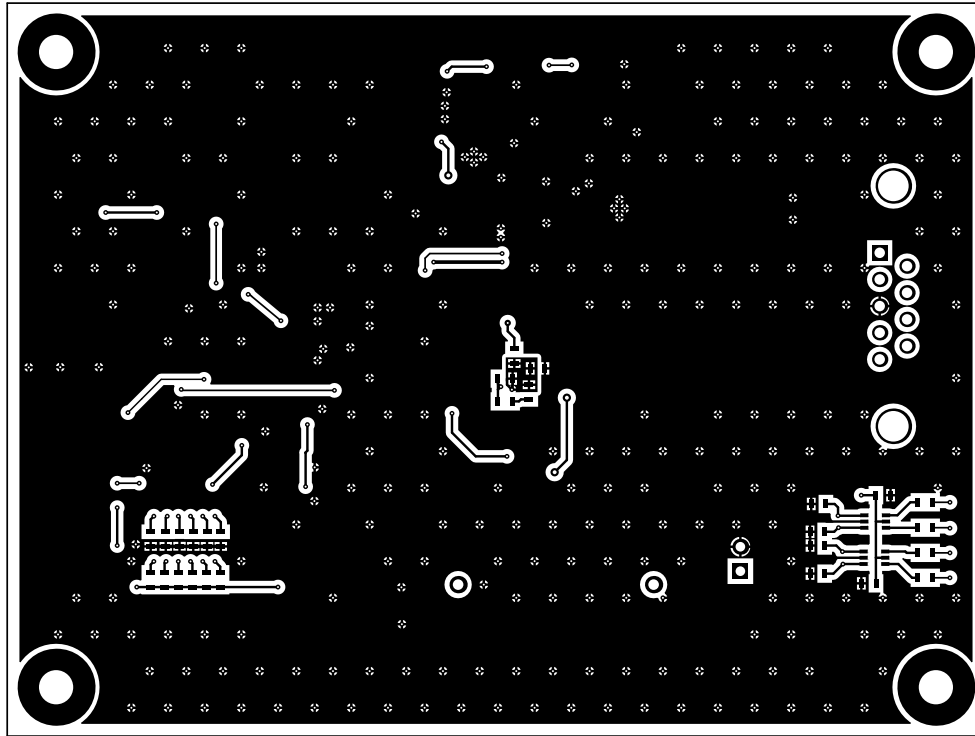
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01429	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01429		
PLOT NAME = Top Overlay	GENERATED : 7/18/2017	1:58:40 PM	TEXAS INSTRUMENTS



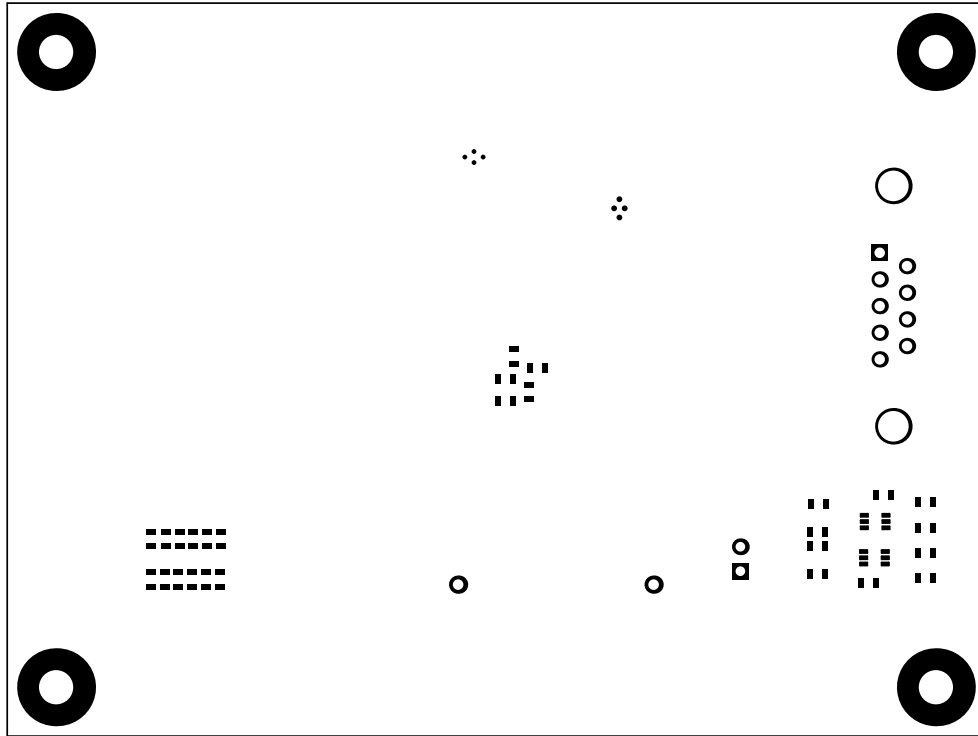
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01429	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01429		
PLOT NAME = Top Solder Mask	GENERATED : 7/18/2017 1:58:41 PM	TEXAS INSTRUMENTS	



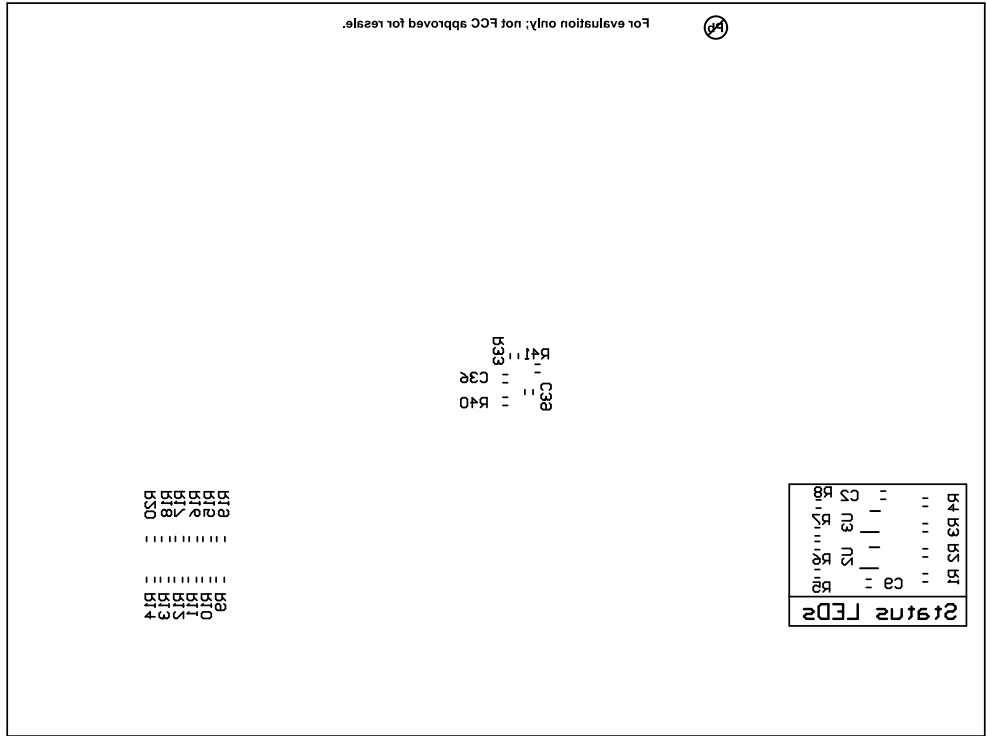
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01429	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01429		
PLOT NAME = Top Layer	GENERATED : 7/18/2017 1:58:42 PM	TEXAS INSTRUMENTS	



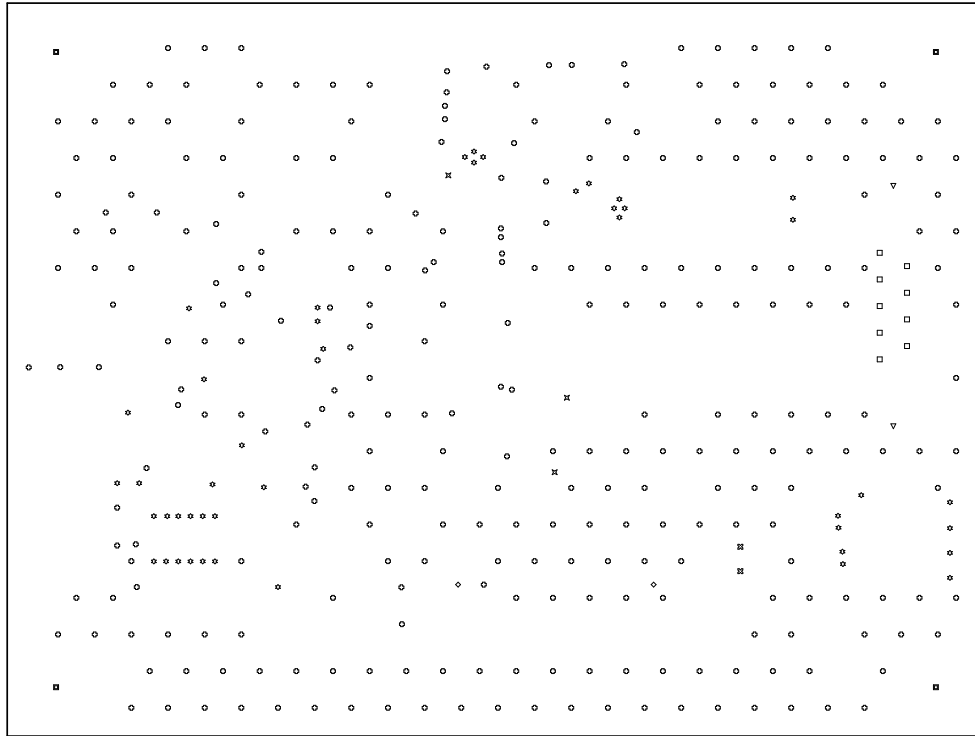
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01429	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01429		
PLOT NAME = Bottom Layer	GENERATED : 7/18/2017 1:58:44 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01429	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01429		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/18/2017 1:58:45 PM	TEXAS INSTRUMENTS	

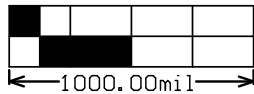
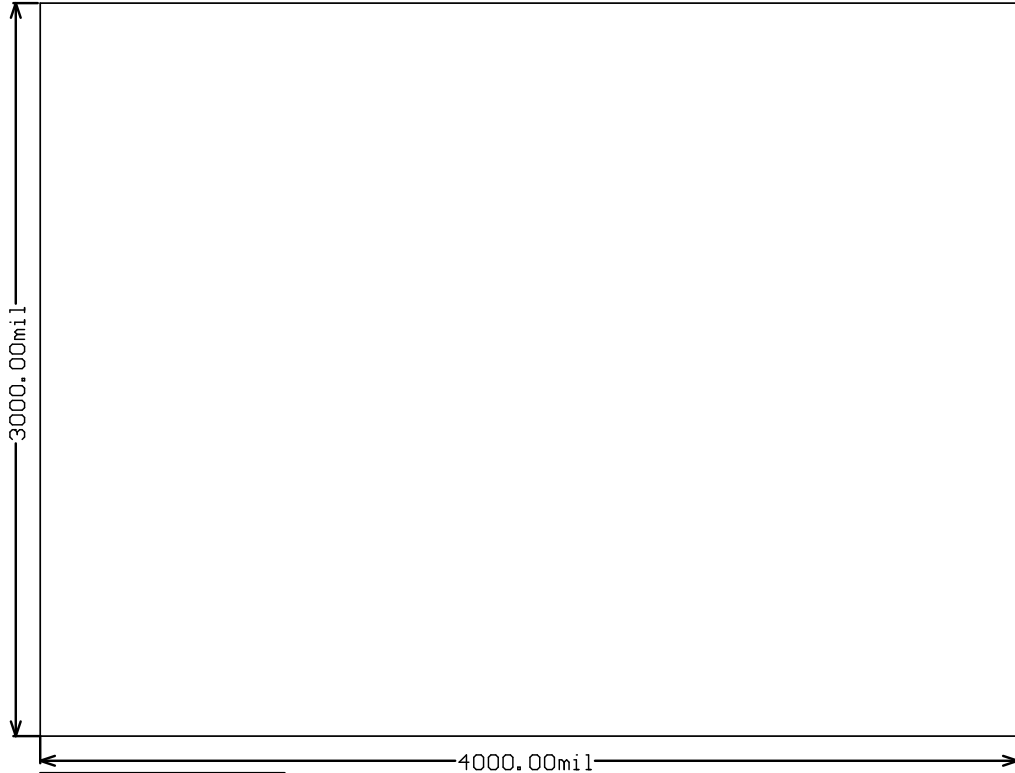


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01429	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01429		
PLOT NAME = Bottom Overlay	GENERATED : 7/18/2017	1:58:46 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊛	45	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	289	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	3	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
□	9	42.91mil (1.090mm)	PTH	Round	Top Layer - Bottom Layer	
◇	2	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	125.20mil (3.180mm)	PTH	Round	Top Layer - Bottom Layer	
■	4	140.00mil (3.556mm)	PTH	Round	Top Layer - Bottom Layer	
	356 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01429	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01429		
PLOT NAME = Drill Drawing	GENERATED : 7/18/2017	1:58:47 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01429	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01429		
PLOT NAME = Board Dimensions	GENERATED : 7/18/2017 1:58:50 PM	TEXAS INSTRUMENTS	



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